

#### **General Description**

The MAX9400/MAX9402/MAX9403/MAX9405 are extremely fast, low-skew quad LVECL/ECL or LVPECL/ PECL buffer/receivers designed for high-speed data and clock driver applications. These devices feature an ultra-low propagation delay of 335ps and channel-tochannel skew of 16ps in asynchronous mode with 86mA supply current.

The four channels can be operated synchronously with an external clock, or in asynchronous mode determined by the state of the SEL input. An enable input provides the ability to force all the outputs to a differential low state.

A variety of input and output terminations are offered for maximum design flexibility. The MAX9400 has open inputs and open emitter outputs. The MAX9402 has open inputs and  $50\Omega$  series outputs. The MAX9403 has  $100\Omega$  differential input impedance and open emitter outputs. The MAX9405 has  $100\Omega$  differential input impedance and  $50\Omega$  series outputs.

These devices operate with a supply voltage of (V<sub>CC</sub> - $V_{EE}$ ) = 2.375V to 5.5V, and are specified for operation from -40°C to +85°C. These devices are offered in space-saving 32-pin 5mm × 5mm TQFP and 32-lead 5mm × 5mm QFN packages.

#### **Applications**

Data and Clock Driver and Buffer Central Office Backplane Clock Distribution **DSLAM** Backplane Base Station **ATE** 

Functional Diagram appears at end of data sheet.

#### **Features**

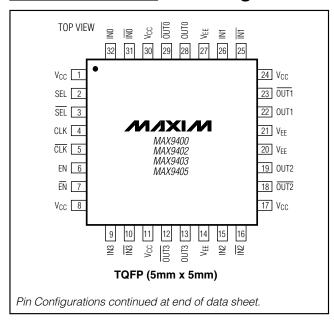
- ♦ 400mV Differential Output at 3.0GHz Data Rate
- ♦ 335ps Propagation Delay in Asynchronous Mode
- ♦ 8ps Channel-to-Channel Skew in Synchronous Mode
- ♦ Integrated 50Ω Outputs (MAX9402/MAX9405)
- ♦ Integrated 100Ω Inputs (MAX9403/MAX9405)
- ♦ Synchronous/Asynchronous Operation

#### **Ordering Information**

PART	TEMP RANGE	PIN- PACKAGE	DATA INPUT	ОUТРUТ
MAX9400EHJ	-40°C to +85°C	32 TQFP	Open	Open
MAX9400EGJ*	-40°C to +85°C	32 QFN	Open	Open
MAX9402EHJ	-40°C to +85°C	32 TQFP	Open	$50\Omega$
MAX9402EGJ*	-40°C to +85°C	32 QFN	Open	$50\Omega$
MAX9403EHJ	-40°C to +85°C	32 TQFP	100Ω	Open
MAX9403EGJ*	-40°C to +85°C	32 QFN	$100\Omega$	Open
MAX9405EHJ	-40°C to +85°C	32 TQFP	100Ω	$50\Omega$
MAX9405EGJ*	-40°C to +85°C	32 QFN	$100\Omega$	$50\Omega$

<sup>\*</sup>Future product—contact factory for availability.

#### **Pin Configurations**



MIXIM

Maxim Integrated Products 1

#### **ABSOLUTE MAXIMUM RATINGS**

,	V <sub>CC</sub> to V <sub>EE</sub>	0.3V to +6V
	Inputs to VEE0.3	$V$ to ( $V_{CC} + 0.3V$ )
	Differential Input Voltage	±3V
	Continuous Output Current	50mA
	Surge Output Current	
	Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
	32-Pin 5mm x 5mm TQFP	
	(derate 9.5mW/°C above +70°C)	761mW
	32-Lead 5mm x 5mm QFN	
	(derate 21.3mW/°C above +70°C)	1.7W
,	Junction-to-Ambient Thermal Resistance in Stil	l Air
	32-Pin 5mm x 5mm TQFP	+105°C/W
	32-Lead 5mm x 5mm QFN	+47°C/W

Junction-to-Ambient Thermal Resistance with 500LFPM Airflow	
32-Pin 5mm x 5mm TQFP	+73°C/W
Junction-to-Case Thermal Resistance	
32-Pin 5mm x 5mm TQFP	+25°C/W
32-Lead 5mm x 5mm QFN	+2°C/W
Operating Temperature Range	40°C to +85°C
Junction Temperature	
Storage Temperature Range	
ESD Protection	
Human Body Model (Inputs and Outputs)	2kV
Soldering Temperature (10s)	+300°C
= : ' '	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} - V_{EE} = 2.375V \text{ to } 5.5V, \text{ MAX9400/MAX9403} \text{ outputs terminated with } 50\Omega \pm 1\% \text{ to } V_{CC} - 2.0V. \text{ Typical values are at } V_{CC} - V_{EE} = 3.3V, V_{IHD} = V_{CC} - 0.9V, V_{ILD} = V_{CC} - 1.7V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$  (Notes 1, 2, and 3)

PARAMETER	SYMBOL		MIN	TYP	MAX	UNITS	
INPUTS (IN_, IN_, CLK, CLK, EN	, EN, SEL, S	EL)					
Differential Input High Voltage	VIHD	Figure 1		V <sub>EE</sub> + 1.4		Vcc	V
Differential Input Low Voltage	V <sub>ILD</sub>	Figure 1		V <sub>EE</sub>		V <sub>CC</sub> - 0.2	V
Differential Input Voltage	V <sub>ID</sub>	Figure 1	V <sub>CC</sub> - V <sub>EE</sub> < +3.0V			V <sub>CC</sub> - V <sub>EE</sub>	V
			V <sub>CC</sub> - V <sub>EE</sub> ≥ +3.0V	0.2		3.0	
land Company		MAX9400/ MAX9402	EN, EN, SEL, SEL, IN_, IN_, CLK, or CLK = VIHD or VILD	-10		25	
Input Current	lih, lil	MAX9403/ MAX9405	EN, EN, SEL, SEL, CLK, or CLK = V <sub>IHD</sub> or V <sub>ILD</sub>	-10		25	μA
Differential Input Resistance	RIN	MAX9403/MA	X9405	86		114	Ω
OUTPUTS (OUT_, OUT_)							
Differential Output Voltage	V <sub>OH</sub> -	Figure 1		600	660		mV
Output Common-Mode Voltage	Vосм	Figure 1		V <sub>CC</sub> -	V <sub>CC</sub> - 1.25	V <sub>CC</sub> -	V
Internal Current Source	ISINK	MAX9402/MAX9405, Figure 2		6.5	8.3	10	mA
Output Impedance	R <sub>OUT</sub>	MAX9402/MAX9405, Figure 2		40	50	60	Ω
POWER SUPPLY							
Supply Current	IEE	MAX9402/MA		150	180	mA	
	'EE	MAX9400/MA	X9403		86	118	IIIA

#### **AC ELECTRICAL CHARACTERISTICS**

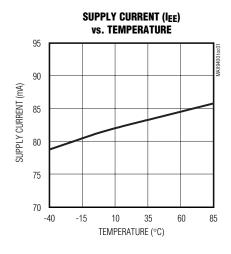
 $(V_{CC} - V_{EE} = 2.375 V \text{ to } 5.5 V)$ , outputs terminated with  $50\Omega \pm 1\%$  to  $V_{CC} - 2.0 V$ , enabled, CLK = 3.2 GHz,  $f_{\text{IN}} = 1.6 \text{GHz}$ , input transition time = 125 ps (20% to 80%),  $V_{\text{IHD}} = V_{\text{EE}} + 1.2 V$  to  $V_{\text{CC}}$ ,  $V_{\text{ILD}} = V_{\text{EE}}$  to  $V_{\text{CC}} - 0.2 V$ ,  $V_{\text{IHD}} - V_{\text{ILD}} = 0.2 V$  to smaller of  $I_{\text{CC}} - V_{\text{EE}} = 3.3 V$ ,  $I_{\text{IHD}} = I_{\text{CC}} - 0.9 V$ ,  $I_{\text{ILD}} = I_{\text{CC}} = 1.7 V$ ,  $I_{\text{CC}} = 1.7$ 

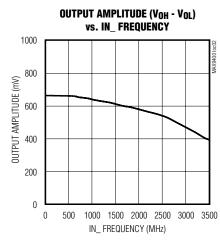
PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS
IN-to-OUT Differential	tPLH1	MAX9400/MAX9403	CEL high Figure 2	237	335	437	
Propagation Delay	tPHL1	MAX9402/MAX9405	SEL = high, Figure 3	237	335	437	ps
CLK-to-OUT Differential	t <sub>PLH2</sub>	MAX9400/MAX9403	CEL Joyr Figure 4	397	475	597	20
Propagation Delay	tPHL2	MAX9402/MAX9405	SEL = low, Figure 4	397	475	597	ps
IN-to-OUT Channel-to-Channel Skew (Note 5)	tskD1	SEL = high			16	80	ps
CLK-to-OUT Channel-to- Channel Skew (Note 5)	tskD2	SEL = low			8	55	ps
Maximum Clock Frequency	fCLK(MAX)	V <sub>OH</sub> -V <sub>OL</sub> ≥500mV, S	EL = low	3.0			GHz
Maximum Data Frequency	fIN(MAX)	V <sub>OH</sub> -V <sub>OL</sub> ≥ 400mV, S	EL = high	2			GHZ
Added Dandem Litter (Note 6)	+	SEL = low, $f_{CLK} = 3.0$	SEL = low, f <sub>CLK</sub> = 3.0GHz clock, f <sub>IN</sub> = 1.5GHz		0.64	1.3	DO (D) 10)
Added Random Jitter (Note 6)	t <sub>RJ</sub>	SEL = high, f <sub>IN</sub> = 2GH	łz		0.74	1.5	ps(RMS)
Added Deterministic Jitter		SEL = low, $f_{CLK} = 3.00$ $2^{23} - 1$ PRBS pattern		17	30	20(2.5)	
(Note 6)	tDJ	SEL = high, IN = 2.0G pattern	SEL = high, IN = 2.0Gbps 2 <sup>23</sup> - 1 PRBS pattern		40	55	PS(P-P)
IN-to-CLK Setup Time	ts	Figure 4		80			ps
CLK-to-IN Hold Time	tH	Figure 4		80			ps
Output Rise Time	t <sub>R</sub>	Figure 3			80	120	ps
Output Fall Time	tF	Figure 3			80	120	ps
Propagation Delay Temperature Coefficient	Δt <sub>PD</sub> / ΔT				0.2	1	ps/°C

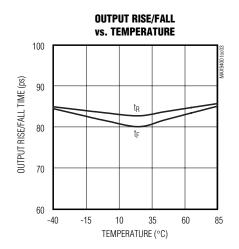
- Note 1: Measurements are made with the device in thermal equilibrium.
- Note 2: Current into a pin is defined as positive. Current out of a pin is defined as negative.
- **Note 3:** DC parameters are production tested at +25°C. DC limits are guaranteed by design and characterization over the full operating temperature range.
- **Note 4:** Guaranteed by design and characterization. Limits are set to ±6 sigma.
- Note 5: Measured between outputs of the same part at the signal crossing points for a same-edge transition.
- Note 6: Device jitter added to the input signal.

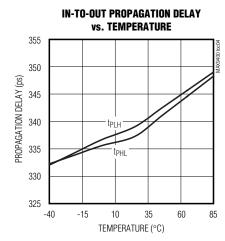
#### **Typical Operating Characteristics**

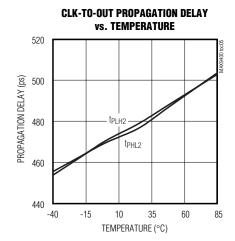
 $(V_{CC} - V_{EE} = 3.3V, MAX9400, outputs terminated with 50\Omega \pm 1\% to V_{CC} - 2.0V, enabled, SEL = high, CLK = 2.0GHz, flN = 1.0GHz, input transition time = 125ps (20% to 80%), V<sub>IHD</sub> = V<sub>CC</sub> - 1.0V, V<sub>ILD</sub> = V<sub>CC</sub> - 1.5V, T<sub>A</sub> = <math>\pm 25^{\circ}$ C, unless otherwise noted.)











### Pin Description

PIN	NAME	FUNCTION
1, 8,11, 17, 24, 30	V <sub>C</sub> C	Positive Supply Voltage. Bypass V <sub>CC</sub> to V <sub>EE</sub> with 0.1µF and 0.01µF ceramic capacitors. Place the capacitors as close to the device as possible with the smaller value capacitor closest to the device.
2	SEL	Noninverting Differential Select Input. Setting SEL = high and $\overline{\text{SEL}}$ = low (differential high) enables all four channels to operate asynchronously. Setting SEL = low and $\overline{\text{SEL}}$ = high (differential low) enables all four channels to operate in synchronous mode.
3	SEL	Inverting Differential Select Input
4	CLK	Noninverting Differential Clock Input
5	CLK	Inverting Differential Clock Input. A rising edge on CLK (and falling on $\overline{\text{CLK}}$ ) transfers data from the inputs to the outputs when SEL = low.
6	EN	Noninverting Differential Output Enable Input. Setting EN = high and $\overline{\rm EN}$ = low (differential high) enables the outputs. Setting EN = low and $\overline{\rm EN}$ = high (differential low) drives outputs low.
7	ĒN	Inverting Differential Output Enable Input
9	IN3	Noninverting Differential Input 3
10	ĪN3	Inverting Differential Input 3
12	OUT3	Inverting Differential Output 3
13	OUT3	Noninverting Differential Output 3
14, 20, 21, 27	VEE	Negative Supply Voltage
15	IN2	Noninverting Differential Input 2
16	ĪN2	Inverting Differential Input 2
18	OUT2	Inverting Differential Output 2
19	OUT2	Noninverting Differential Output 2
22	OUT1	Noninverting Differential Output 1
23	OUT1	Inverting Differential Output 1
25	ĪN1	Inverting Differential Input 1
26	IN1	Noninverting Differential Input 1
28	OUT0	Noninverting Differential Output 0
29	OUT0	Inverting Differential Output 0
31	ĪNO	Inverting Differential Input 0
32	IN0	Noninverting Differential Input 0
	EP	Exposed Paddle (MAX940_EGJ only). Connected to V <sub>EE</sub> internally. See package dimensions.

#### **Detailed Description**

The MAX9400/MAX9402/MAX9403/MAX9405 are extremely fast, low-skew quad LVECL/ECL or LVPECL/PECL buffer/receivers designed for high-speed data and clock driver applications. The devices feature an ultra-low propagation delay of 335ps and channel-to-channel skew of 16ps in asynchronous mode with an 86mA supply current.

The four channels can be operated synchronously with an external clock, or in asynchronous mode, determined by the state of the SEL input. An enable input provides the ability to force all the outputs to a differential low state.

A variety of input and output terminations are offered for maximum design flexibility. The MAX9400 has open inputs and open-emitter outputs. The MAX9402 has open inputs and  $50\Omega$  series outputs. The MAX9403 has  $100\Omega$  differential input impedance and open-emitter outputs. The MAX9405 has  $100\Omega$  differential input impedance and  $50\Omega$  series outputs.

#### Supply Voltage

The MAX9400/MAX9402/MAX9403/MAX9405 are designed for operation with a single supply. Using a single negative supply of VEE = -2.375V to -5.5V (VCC = ground) yields LVECL/ECL-compatible input and output levels. Using a single positive supply of VCC = 2.375V to 5.5V (VEE = ground) yields LVPECL/PECL input and output levels.

#### **Data Inputs**

The MAX9400/MAX9402 have open inputs and require external termination. The MAX9403/MAX9405 have integrated  $\underline{100\Omega}$  differential input termination resistors from IN\_ to  $\overline{\text{IN}}_{-}$ , reducing external component count.

#### **Outputs**

The MAX9402/MAX9405 have internal  $50\Omega$  series output termination resistors and 8mA internal pulldown current sources. Using integrated resistors reduces external component count.

The MAX9400/MAX9403 have open-emitter outputs. An external termination is required. See the *Output Termination* section.

#### **Enable**

Setting EN = high and  $\overline{\text{EN}}$  = low enables the device. Setting EN = low and  $\overline{\text{EN}}$  = high forces the outputs to a differential low, and all changes on CLK, SEL, and IN\_ are ignored.

#### **Asynchronous Operation**

Setting SEL = high and SEL = low enables the four channels to operate independently as buffer/receivers.

The CLK signal is ignored in this mode. In asynchronous mode, the CLK signal should be set to either a logic low or high state to minimize noise coupling.

#### **Synchronous Operation**

Setting SEL = low and  $\overline{SEL}$  = high enables all four channels to operate in synchronous mode. In this mode, buffered inputs are clocked into flip-flops simultaneously on the rising edge of the differential clock input (CLK and  $\overline{CLK}$ ).

#### **Differential Signal Input Limit**

The maximum signal magnitude of the differential inputs is VCC - VEE or 3V, whichever is less.

#### Applications Information

#### **Input Bias**

Unused inputs should be biased or driven as shown in Figure 5. This avoids noise coupling that might cause toggling at the unused outputs.

#### **Output Termination**

Terminate open-emitter outputs (MAX9400/MAX9403) through  $50\Omega$  to VCC - 2V or use an equivalent Thevenin termination. Terminate both outputs and use identical termination on each for the lowest output-to-output skew. When a single-ended signal is taken from a differential output, terminate both outputs. For example, if OUT\_ is used as a single-ended output, terminate both OUT and  $\overline{OUT}$ .

Ensure that the output currents do not exceed the current limits as specified in the *Absolute Maximum Ratings* table. Under all operating conditions, the device's total thermal limits should be observed.

#### **Power-Supply Bypassing**

Adequate power-supply bypassing is necessary to maximize the performance and noise immunity. Bypass VCC to VEE with high-frequency surface-mount ceramic 0.1µF and 0.01µF capacitors as close to the device as possible with the 0.01µF capacitor closest to the device pins. Use multiple bypass vias for connection to minimize inductance.

#### **Circuit Board Traces**

Input and output trace characteristics affect the performance of the MAX9400/MAX9402/MAX9403/MAX9405. Connect each of the inputs and outputs to a  $50\Omega$  characteristic impedance trace. Avoid discontinuities in differential impedance and maximize common-mode noise immunity by maintaining the distance between differential traces and avoid sharp corners. Minimize the number of vias to prevent impedance discontinuities. Reduce reflections by maintaining the  $50\Omega$  characteristics.

acteristic impedance through connectors and across cables. Minimize skew by matching the electrical length of the traces.

Chip Information

TRANSISTOR COUNT: 713
PROCESS: Bipolar

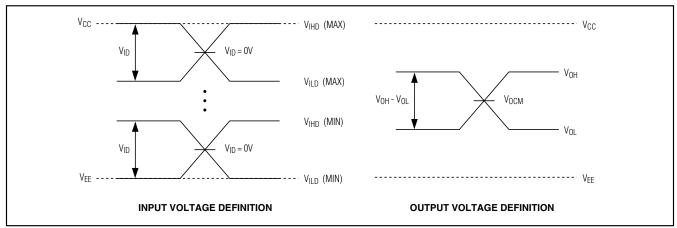


Figure 1. Input and Output Voltage Definitions

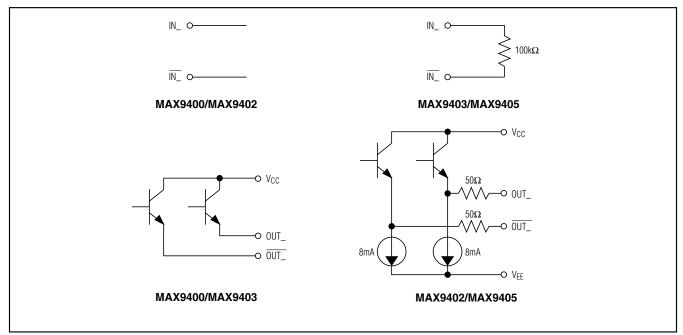


Figure 2. Input and Output Configurations

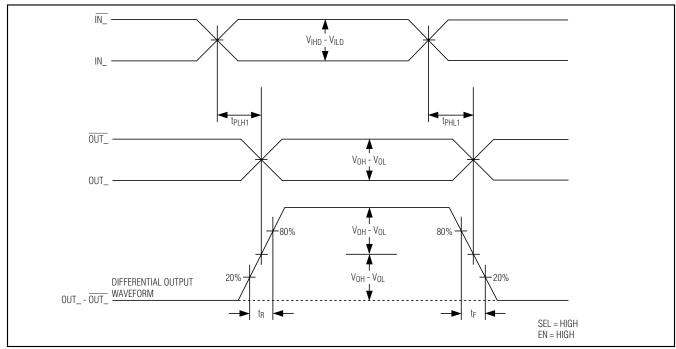


Figure 3. IN-to-OUT Propagation Delay and Transition Timing Diagram

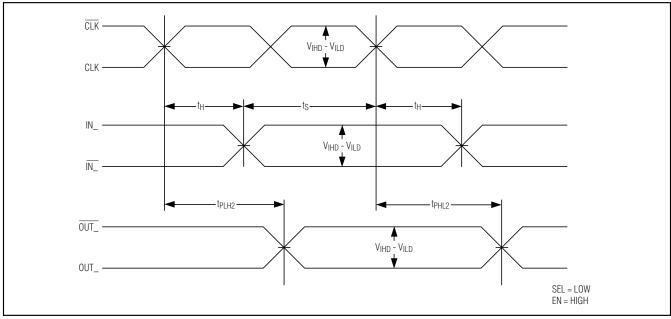


Figure 4. CLK-to-OUT Propagation Delay Timing Diagram

8 \_\_\_\_\_\_ *NIXI/*M

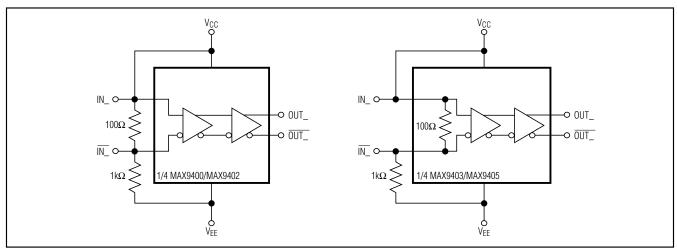
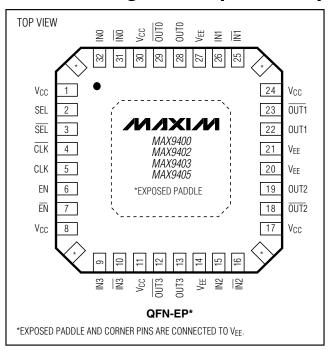
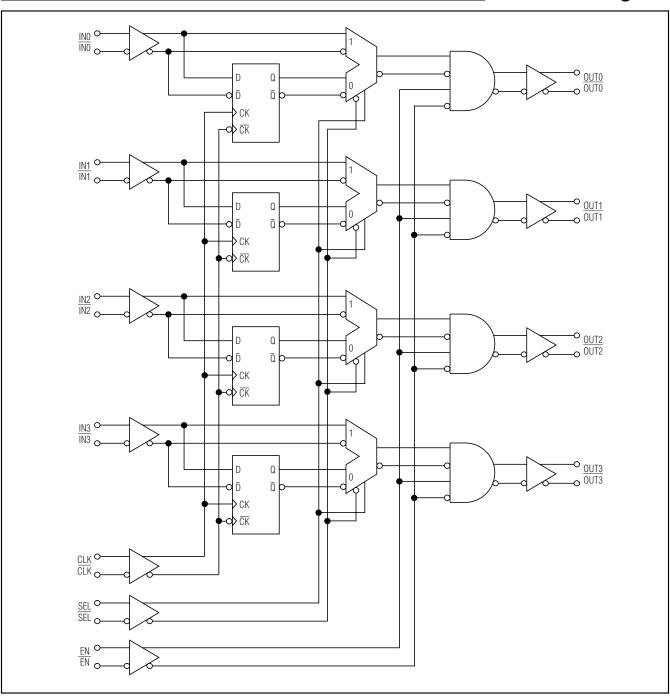


Figure 5. Input Bias Circuits for Unused Inputs

### Pin Configurations (continued)



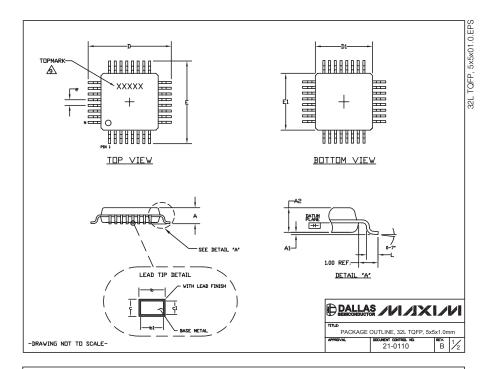
### Functional Diagram



10 \_\_\_\_\_\_\_//IXI/M

#### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



- ITES:
  ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5-1982.
  DATUM PLANE □□□ IS LOCATED AT MOLD PARTING LINE AND
  COINCIDENT VITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT
  BOTTOM OF PARTING LINE.
  DIMENSIONS DI AND EI D

- ALLOWABLE MOLD PROTRUSION IS 0.25 MM IN DI AND EI DIMENSIONS.
  THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.
  DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE & DIMENSION AT MAXIMUM MATERIAL CONDITION.
  ALL DIMENSIONS ARE IN MILLIMETERS.
  THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95, REGISTRATION MS-026.
  LEADS SHALL BE COPLANAR WITHIN .004 INCH.

ъ.	LEADS 2	HALL BE	CUPLAR	NAK MILHI	N JUU4 INCH.		
9.	TOPMARK	SHOWN	IS FOR	PACKAGE	DRIENTATION	REFERENCE	DNLY

	JEDEC VARIATIONS DIMENSIONS IN MILLIMETERS							
	AA	ıΑ						
	5×5×1	.0 MM 0.						
	MIN.	MIN. MAX.						
Α	**	1.20						
A <sub>1</sub>	0.05 0.15							
Ae	0.95	1.05						
D	6.80	7.20						
D <sub>1</sub>	4.80	5.20						
E	6.80	7.20						
E <sub>1</sub>	4.80	5.20						
L	0.45	0.75						
N	3	2						
e	0.50	BSC.						
ю	0.17	0.27						
b1	0.17	0.23						
c	0.09	0.20						
<b>c</b> 1	0.09	0.16						

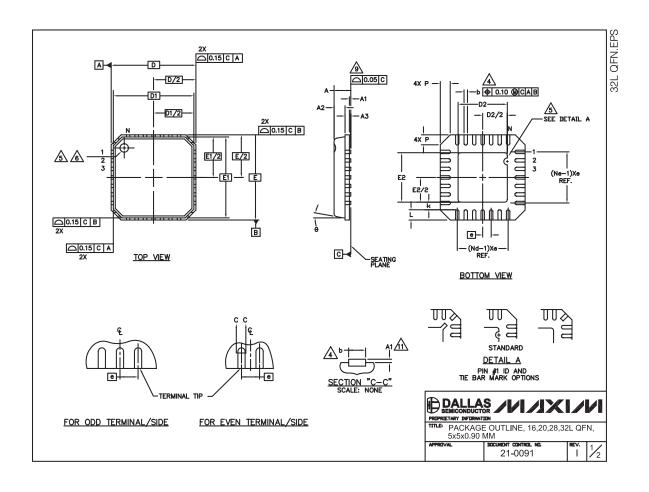


21-0110

-DRAWING NOT TO SCALE-

#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.



#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.

					COMM	ON DIME	NSIONS							
PKG		16L 5x5			20L 5x5			28L 5x5		32L 5x5				
SYMBOL	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.80	0.90	1.00	0.80	0.90	1.00	0.80	0.90	1.00	0.80	0.90	1.00		
A1	0.00	0.01	0.05	0.00	0.01	0.05	0.00	0.01	0.05	0.00	0.01	0.05		
A2	0.00	0.65	1.00	0.00	0.65	1.00	0.00	0.65	1.00	0.00	0.65	1.00		
A3		0.20 REF	-		0.20 REF			0.20 REF			0.20 REF		0.20 REF	
ь	0.28	0.33	0.40	0.23	0.28	0.35	0.18	0.23	0.30	0.18	0.23	0.30		
D	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10		
D1		4.75 BS	Ċ		4.75 BS0			4.75 BS			4.75 BSC			
Е	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10		
E1		4.75 BS	c		4.75 BS0		4.75 BSC				4.75 BS0	;		
9		0.80 BS	С		0.65 BSC	;		0.50 BS	С	0.50 BSC				
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-		
L	0.35	0.55	0.75	0.35	0.55	0.75	0.35	0.55	0.75	0.30	0.40	0.50		
N		16			20			28			32			
ND		4		5			7			8				
NE	4 5			7			8							
Р	0.00	0.42	0.60	0.00	0.42	0.60	0.00	0.42	0.60	0.00	0.42	0.60		
9	0.		12°	0.		12°	0.		12°	0.		12*		

EXPOSED PAD VARIATIONS							
PKG.		D2		E5			
CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
G1655-3	2.95	3.10	3.25	2.95	3.10	3.25	
G2055-1	2.55	2.70	2.85	2.55	2.70	2.85	
G2055-2	2.95	3.10	3.25	2.95	3.10	3.25	
G2855-1	2.55	2.70	2.85	2.55	2.70	2.85	
G2855-2	2.95	3.10	3.25	2.95	3.10	3.25	
G3255-1	2.95	3.10	3.25	2.95	3.10	3.25	

#### NOTES:

- 1. DIE THICKNESS ALLOWABLE IS 0.305mm MAXIMUM (.012 INCHES MAXIMUM)
- 2. DIMENSIONING & TOLERANCES CONFORM TO ASME Y14.5M. 1994.
- 3. N IS THE NUMBER OF TERMINALS.

  Nd IS THE NUMBER OF TERMINALS IN X-DIRECTION & No IS THE NUMBER OF TERMINALS IN Y-DIRECTION.
- AL DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25mm FROM TERMINAL TIP.
- THE PIN \$1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR INK/LASER MARKED.

  DETAILS OF PIN \$1 IDENTIFIER IS OPTIONAL, BUT MUST BE LOCATED WITHIN ZONE INDICATED.
- 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- 7. ALL DIMENSIONS ARE IN MILLIMETERS.
- 8. PACKAGE WARPAGE MAX 0.05mm.
- APPLIED FOR EXPOSED PAD AND TERMINALS.

  EXCLUDE EMBEDDED PART OF EXPOSED PAD FROM MEASURING.
- 10. MEETS JEDEC MO220; EXCEPT DIMENSION "b".
- APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.
- 12. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES).



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.